

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		:2 and (encapsulant or encpasulate or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:19
		@ad<"20000428") and (wafer adj (scale or processing)) and (ball or balls or solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:18
S1	1	("6306680").PN.	USPAT; USOCR	OR	OFF	2005/10/14 21:17
S2	1082	(@ad<"20000428") and (wafer adj (scale or processing)) and (ball or balls or solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:52
S3	367	S2 and (encapsulant or encpasulate or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:22
S4	1	("6908784").PN.	USPAT; USOCR	OR	OFF	2005/10/14 21:25
S5	0	("L4and(cut or cutting or saw or sawing or dicing)").PN.	USPAT; USOCR	OR	OFF	2005/10/14 21:25
S6	269	S3 and (cut or cutting or saw or sawing or dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:30
S7	3694	(wafer same (encapsulate or epoxy or encapsulant)) and (cut or cutting or saw or sawing or dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:52
S8	378	S7 and (@ad<"20000428") and (CMP or polish or polishing or grind or grinding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46

S9	346	S8 not S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:32
S10	1064	(wafer with (grind or grinding)) and (cut or cutting or saw or sawing or dicing) and (ball or balls or solder or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46
S11	1458	(wafer with (grind or grinding or cmp or polish)) and (cut or cutting or saw or sawing or dicing) and (ball or balls or solder or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46
S12	2316	(wafer with (grind or grinding or cmp or polish\$3)) and (cut or cutting or saw or sawing or dicing) and (ball or balls or solder or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46
S13	698	S12 and (@ad<"20000428")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:47
S14	615	S13 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:47
S15	590	S13 not S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:03
S16	8	(("5798285") or ("5801073") or ("5841193") or ("5854085") or ("5915170") or ("6114753") or ("6166436") or ("6194290")).PN.	USPAT; USOCR	OR	OFF	2005/10/14 22:03
S17	905	(@ad<"20000428") and ("csp" or (chip near scale)) and (encapsulate or epoxy or encapsulant or polymer) and (ball or balls or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:10

S18	893	S17 not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:10
S19	775	S7 and (wafer with (tape or polyimide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:52
S20	117	S19 and (@ad<"20000428") and (ball or balls or solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:54